

AMENDMENTS TO THE SPECIFICATION

- 1. After the title and before the first paragraph, please insert the following paragraph:**

THIS APPLICATION IS A U.S. NATIONAL PHASE APPLICATION OF
PCT INTERNATIONAL APPLICATION PCT/JP2004/008850, filed June 17, 2004.

- 2. Please replace the paragraph beginning at page 30, line 25 with the following rewritten paragraphs. This is due to a typographical error.**

By fixing film 10 for suppressing conduction of radiation heat like above of the invention to a location where requiring to suppress against radiation-heat conduction, effective heat insulation is available. Application point examples include building components such as housing or factory roofs, computers and character printers, office machines such as copiers at their points requiring heat shield, fluorescent lamps etc. incorporating inverters in i.e. include positions between a heat generator arranged in the main body and a toner or an interior precise component weak to heat. The resin film is to be used in an extreme surface directed to such a heat generation source, followed by layering a metal foil thereon. Fluorescent lamps etc. incorporating inverters can also employ it.

- 3. Please replace the paragraph beginning at page 52, line 13 with the following rewritten paragraph. This is due to a typographical error.**

Embodiment 14 explains vacuum heat-insulating material 16 using envelope material 18 of embodiment 10. The envelope material based on example-5 embodiment 14 has a thermal bonding layer, a gas-barrier layer and a core material that are similar in specification to embodiment 13.

4. Please replace the paragraph beginning at page 53, line 9 with the following rewritten paragraph. This is due to a typographical error.

Embodiment 15 explains vacuum heat-insulating material 16 using envelope material 18 of embodiment 11. The envelope material in example-6 embodiment 15 has a thermal bonding layer, a gas-barrier layer and a core material that are similar in specification to embodiment 13.

5. Please replace the paragraph beginning at page 44, line 2 with the following rewritten paragraph. This is due to a typographical error.

The IR entered at a surface of resin film 11 reaches, at an absorptivity of lower than 25%, metal foil [[6]] 4 and reflects thereupon. The reflected IR is allowed to transmit resin film 11 at an absorptivity of lower than 25% thereof. As a result, there is no possibility that the increase in the in-solid heat conductivity, due to the IR absorption in resin film 11, surpasses the IR reflection effect based on metal foil 4.

6. Please replace the paragraph beginning at page 15, line 11 with the following rewritten paragraph. This is due to a typographical error.

By fixing film [[11]] 10 for suppressing conduction of radiation heat of this embodiment to a location where radiation-heat conduction is required to suppress, an effective heat insulation effect can be obtained.